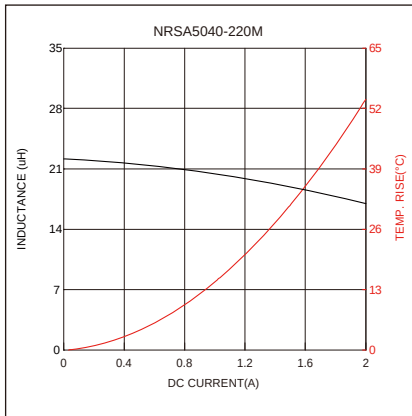
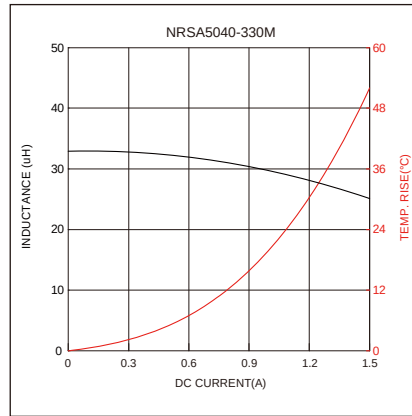
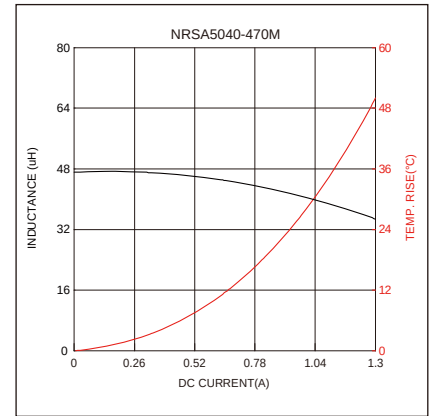
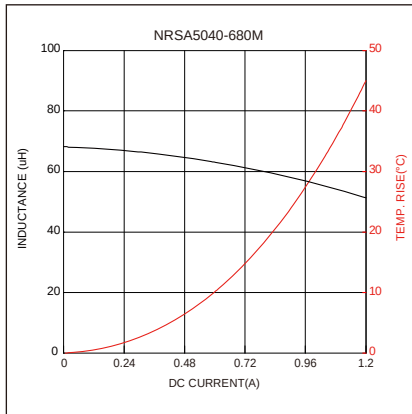
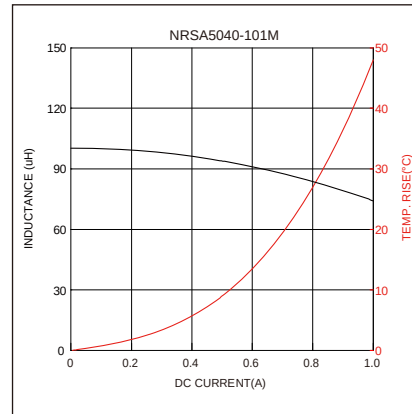
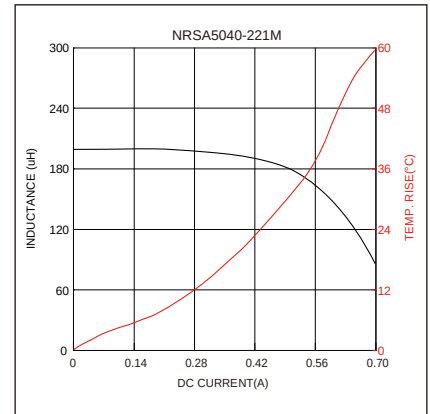


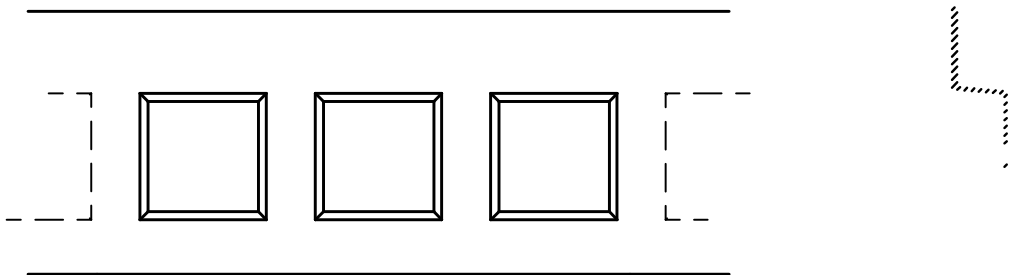


Soldering Reflow:

Preheat condition: 150 ~200℃ / 60~120 sec.
 Allowed time above 217℃ : 60~90 sec.
 Max temperature: 260℃ .
 Allowed Reflow time: 2x max.

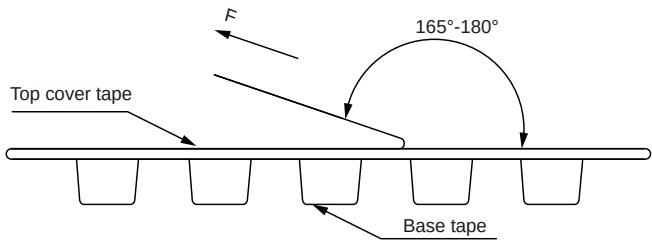
Packaging Information:

Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
NRSA5040	5.3±0.1	5.3±0.1	1.5±0.1	4.0±0.1	8.0±0.1	12.0±0.3	4.2±0.1	1.75±0.1	0.40±0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.3 to 1.17 N



Reel Dimension: [mm]



Packaging Quantity: